

PATENT

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March 3, 2004  
Date

Ayesha J. Shaikh  
Ayesha J. Shaikh

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. No. : 10/666,393

Confirmation No. : 7509

Applicant : Philip Neaves

Filed : September 17, 2003

Attorney Docket No.: 501298.02

Art Unit : 2812

Customer No. : 27,076

Examiner : Not Yet Assigned

Title : SYSTEM AND METHOD FOR BALANCING CAPACITIVELY COUPLED SIGNAL LINES

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**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97 through 1.98, applicant wishes to make known to the Patent and Trademark Office the references set forth on the attached form PTO-1449. Copies of the cited foreign patent and non-patent literature references, as required under 37 C.F.R. § 1.98(a)(2), are enclosed. Copies of the cited U.S. patents and U.S. patent application publications will not be submitted herewith in accordance with the waiver by the Office of the requirement under 37 C.F.R. § 1.98(a)(2)(i) for U.S. national patent applications filed after June 30, 2003. Although the aforesaid references are made known to the Patent and Trademark Office in compliance with applicant's duty to disclose all information he is aware of which is believed relevant to the examination of the above-identified application, applicant believes that his invention is patentable.

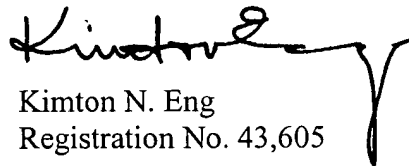
Applicant also wishes to make known to the Patent and Trademark Office that an application, Serial No. 10/691,020, describing and claiming subject matter that is similar to the subject matter of this application, was filed on October 21, 2003, which claims priority to United Kingdom Patent Application No. 0319680.5, filed August 21, 2003. This related application, as well as any prior art cited therein, may be material to the examination of this application. A copy of this related application as filed is submitted herewith in accordance with 37 C.F.R. § 1.98(d).

Applicant also wishes to make known to the Patent and Trademark Office that an application, Serial No. 10/779,305, describing and claiming subject matter that is similar to the subject matter of this application, was filed on February 13, 2004, which claims priority to United Kingdom Patent Application No. 0323992.8, filed October 13, 2003. This related application, as well as any prior art cited therein, may be material to the examination of this application. A copy of this related application as filed is submitted herewith in accordance with 37 C.F.R. § 1.98(d).

Please acknowledge receipt of this Supplemental Information Disclosure Statement and kindly make the cited references of record in the above-identified application.

Respectfully submitted,

DORSEY & WHITNEY LLP

  
Kimton N. Eng  
Registration No. 43,605

KNE:ajs

Enclosures:

Postcard

Form PTO-1449

Cited References (11)

Copies of Related Applications (2)

1420 Fifth Avenue, Suite 3400

Seattle, WA 98101

Telephone (206) 903-8800

Facsimile (206) 903-8820

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FORM PTO-1449  
(REV. 7-80)U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.  
501298.02APPLICATION NO.  
10/666,393

## INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

APPLICANT(S)

Philip Neaves

FILING DATE

September 17, 2003

GROUP ART UNIT

2812

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	6,188,232 B1	02/13/01	Akram et al.	324	755	
	AB	6,285,201 B1	09/04/01	Farnworth et al.	324	755	
	AC	6,357,025 B1	03/12/02	Tuttle	714	724	
	AD	6,368,930 B1	04/09/02	Enquist	438	320	
	AE	6,396,292 B2	05/28/02	Hembree et al.	324	755	
	AF	6,407,566 B1	06/18/02	Brunelle et al.	324	758	
	AG	6,490,188 B2	12/03/02	Nuxoll et al.	365	63	
	AH	6,563,133 B1	05/13/03	Tong	257	52	
	AI	6,563,299 B1	05/13/03	Van Horn et al.	324	158.1	
	AJ	6,620,638 B1	09/16/03	Farrar	438	14	
	AK	6,625,073 B1	09/23/03	Beffa	365	201	
	AL	2001/0054908 A1	12/27/01	Farnworth et al.	324	755	
	AM						
	AN						
	AO						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AP	0 277 764 A3	01/27/88	EP			X	
	AQ	0 492 806 A3	11/26/91	EP			X	
	AR	0 805 356 A3	04/22/98	EP			X	
	AS	2 353 401 A	02/21/01	GB			X	
	AT	2 353 402 A	02/21/01	GB			X	
	AU						X	
	AV							

EXAMINER

DATE CONSIDERED

\* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).

FORM PTO-1449 (REV.7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. 501298.02	APPLICATION NO. 10/666,393
<b>INFORMATION DISCLOSURE STATEMENT</b> <i>(Use several sheets if necessary)</i>				APPLICANT(S) Philip Neaves	
				FILING DATE September 17, 2003	GROUP ART UNIT 2812
<b>OTHER PRIOR ART</b> <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>					
	AW	"International Technology Roadmap for Semiconductors", Assembly and Packaging, 2001, pp. 1-21.			
	AX	Karnezos, M. et al., "System in a Package (SiP) Benefits and Technical Issues", in <i>Proceedings of APEX</i> , San Diego, California, 2002, 7 pages.			
	AY	Mick, S. et al., "4Gbps High-Density AC Coupled Interconnection", Department of Electrical and Computer Engineering North Carolina State University, IEEE Custom Integrated Circuits Conference, May 12-16, 2002, pp. 133-140.			
	AZ	"Rapidly Advancing System-in-Package Fabrication Technology", Vol. 20, No.3, 2002, pp. 3-11.			
	BA	Scanlan, C.M. et al., "System-In-Package Technology, Application and Trends", 2001 Proceedings of SMTA International, Rosemont, Illinois, pp. 764-773.			
	BB	Wang, M. et al., "Configurable Area-IO Memory for System-In-A-Package (SiP)", 27 <sup>th</sup> European Solid-State Circuits Conference, September, 2001, 4 pages.			
	BC				
	BD				
	BE				
	BF				
	BG				
	BH				
	BI				
EXAMINER				DATE CONSIDERED	
<b>* EXAMINER:</b> Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).					